Unit: mm

MA2J704 (MA10704)

Silicon epitaxial planar type

For super high speed switching

Features

- Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible
- Small reverse current I_R (About 1/10 of I_R of the ordinary products)

+ 1.25±0.1 - 0.35±0.1	0.7±0.1
	2:5 ^{±0.2}
	international data
5° 0.5±0.1	0.16 ^{+0.1}
0 to 0.1	(0.15)
1 : Anode	
2 : Cathode	C) (; ; 2 E) D 1
EIAJ : SC-76	SMini2-F1 Package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

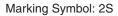
Parameter

Reverse voltage	V _R	20	V
Repetitive peak reverse voltage	V _{RRM}	20	V
Peak forward current	I _{FM}	300	mA
Forward current (Average)	I _{F(AV)}	200	mA
Non-repetitive peak forward surge current *	I _{FSM}	1	А
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Symbol

Rating

Unit



Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

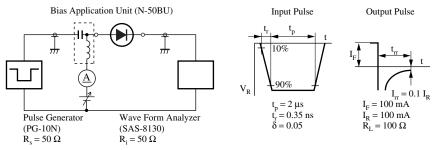
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I _{R1}	$V_R = 10 V$			2	μΑ
	I _{R2}	$V_R = 20 V$			5	
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		30		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		3.0		ns
		$I_{\rm rr}$ = 0.1 I_R , R_L = 100 Ω				

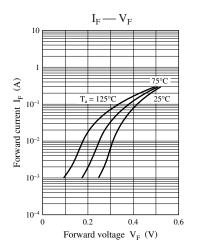
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

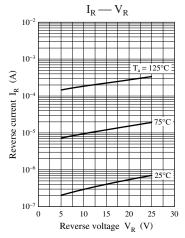
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

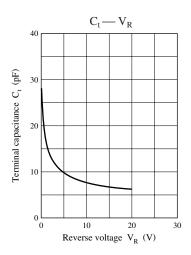
- 3. Absolute frequency of input and output is 1 GHz.
- 4. *: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.







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